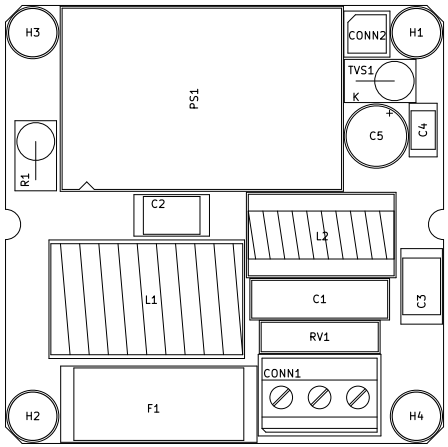
Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Direct Printing	0 mm	White	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Dry Film	0.01 mm	Green	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric 1	core	FR4	1.51 mm		4.5	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Dry Film	0.01 mm	Green	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Direct Printing	0 mm	White	1	0

REVISION HISTORY

ZONE	REV	DESCRIPTION	DATE	APPROVED
	V1R0	First version	2022-04-03	

BOARD CHARACTERISTICS

Copper Layer Count:	2	Board Thickness:	1.6000 mm
Board overall dimensions:	58.0500 mm x 58.0500 mm		
Min track/spacing:	1.0000 mm / 0.1000 mm	Min hole diameter:	0.3000 mm
Copper Finish:	Immersion gold	Impedance Control:	No
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	No		



STATUS Prototype	**TECHNICAL REFERENCE** IRM-03-05	**STANDARD** IS07200-2004	**LICENSE** CC BY-SA	**SIZE** A4
PART NUMBER AE01.07.50.100	**PCB NUMBER** -	**ASSEMBLY NUMBER** -	**ID** -	**SCALE** 1:1
SHEET NAME		**FILE** AE01.07.50.100.kicad_pcb		
DESCRIPTION 230Vac input. 5Vdc/600mA/3W output. European outlet size.			**astroelectronic**	
TITLE IRM-03-05 AC/DC POWER SUPPLY			**VER./REV.** V1R0	**DATE** 2022-04-03	**SHEET** 1/1